

P-Channel Power MOSFET

-60V, -150mA, 8Ω

FEATURES

- Low $R_{DS(ON)}$ to minimize conductive losses
- Logic level
- Low gate charge for fast power switching
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

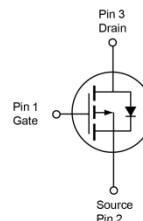
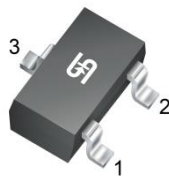
- Low Side Load Switching
- Level Shift Circuits
- General Switch Circuits

KEY PERFORMANCE PARAMETERS

PARAMETER	VALUE	UNIT
V_{DS}	-60	V
$R_{DS(on)}$ (max)	$V_{GS} = -10V$	8
	$V_{GS} = -4.5V$	10
Q_g	1	nC



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Note: MSL 1 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	-60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current (Note 1)	I_D	$T_A = 25^\circ\text{C}$	-150
		$T_A = 125^\circ\text{C}$	-70
Pulsed Drain Current	I_{DM}	-0.6	A
Total Power Dissipation	P_D	$T_A = 25^\circ\text{C}$	357
		$T_A = 125^\circ\text{C}$	71
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

THERMAL PERFORMANCE

PARAMETER	SYMBOL	MAXIMUM	UNIT
Junction to Ambient Thermal Resistance	$R_{\theta JA}$	350	$^\circ\text{C/W}$

Thermal Performance Note: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case-thermal reference is defined at the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design. The $R_{\theta JA}$ limit presented here is based on mounting on a 1 in² pad of 2 oz copper.

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250\mu A$	BV_{DSS}	-60	--	--	V
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = -250\mu A$	$V_{GS(TH)}$	-0.9	-1.5	-2.0	V
Gate-Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	I_{GSS}	--	--	± 100	nA
Drain-Source Leakage Current	$V_{GS} = 0V, V_{DS} = -60V$	I_{DSS}	--	--	-1	μA
	$V_{GS} = 0V, V_{DS} = -60V$ $T_J = 125^\circ\text{C}$		--	--	-100	
Drain-Source On-State Resistance (Note 3)	$V_{GS} = -10V, I_D = -150mA$	$R_{DS(on)}$	--	3.6	8	Ω
	$V_{GS} = -4.5V, I_D = -130mA$		--	3.9	10	
Forward Transconductance (Note 3)	$V_{DS} = -5V, I_D = -150mA$	g_{fs}	--	0.5	--	S
Dynamic (Note 3)						
Total Gate Charge	$V_{GS} = -10V, V_{DS} = -30V,$ $I_D = -150mA$	Q_g	--	1.9	--	nC
Total Gate Charge	$V_{GS} = -4.5V, V_{DS} = -30V,$ $I_D = -130mA$	Q_g	--	1	--	
Gate-Source Charge		Q_{gs}	--	0.3	--	
Gate-Drain Charge		Q_{gd}	--	0.3	--	
Input Capacitance	$V_{GS} = 0V, V_{DS} = -30V$ $f = 1.0MHz$	C_{iss}	--	37	--	pF
Output Capacitance		C_{oss}	--	15	--	
Reverse Transfer Capacitance		C_{rss}	--	7	--	
Switching (Note 3)						
Turn-On Delay Time	$V_{GS} = -10V, V_{DS} = -30V,$ $I_D = -150mA, R_G = 6\Omega$	$t_{d(on)}$	--	10	--	ns
Turn-On Rise Time		t_r	--	15	--	
Turn-Off Delay Time		$t_{d(off)}$	--	21	--	
Turn-Off Fall Time		t_f	--	78	--	
Source-Drain Diode						
Forward Voltage (Note 2)	$V_{GS} = 0V, I_S = -150mA$	V_{SD}	--	--	-1.2	V
Reverse Recovery Time	$I_S = -150mA,$ $dI/dt = 100A/\mu s$	t_{rr}	--	24	--	ns
Reverse Recovery Charge		Q_{rr}	--	14	--	nC

Notes:

1. Silicon limited current only.
2. Pulse test: Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. Switching time is essentially independent of operating temperature.

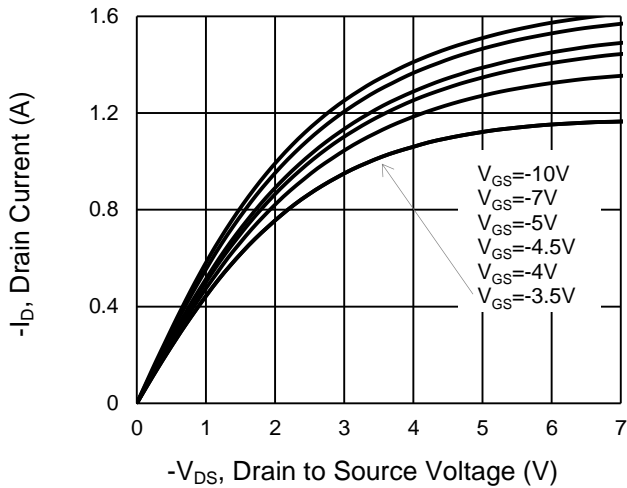
ORDERING INFORMATION

ORDERING CODE	PACKAGE	PACKING
BSS84 RFG	SOT-23	3,000pcs / 7" Reel

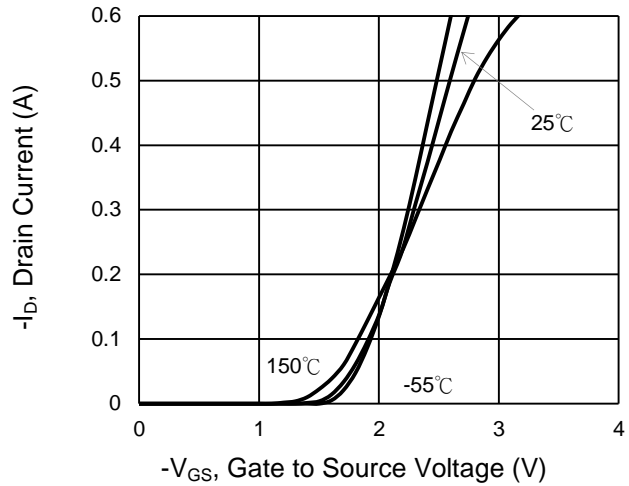
CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

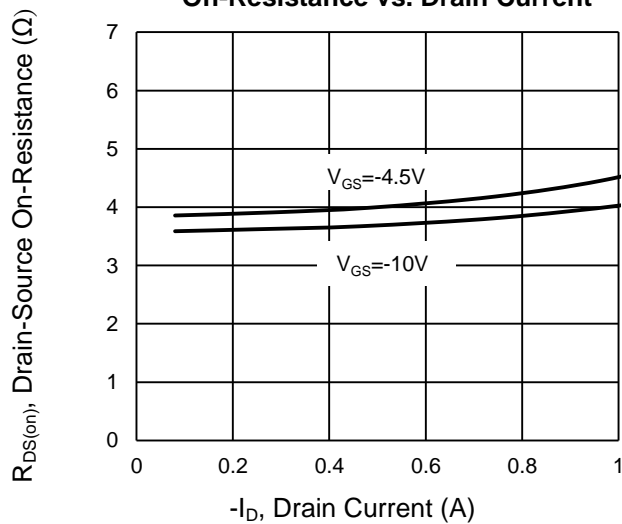
Output Characteristics



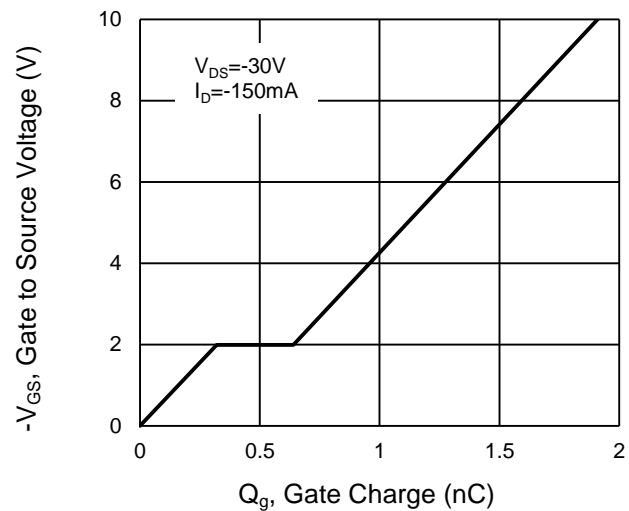
Transfer Characteristics



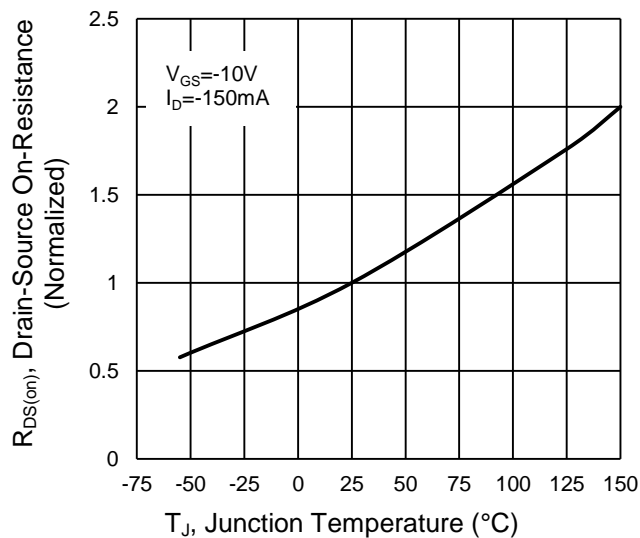
On-Resistance vs. Drain Current



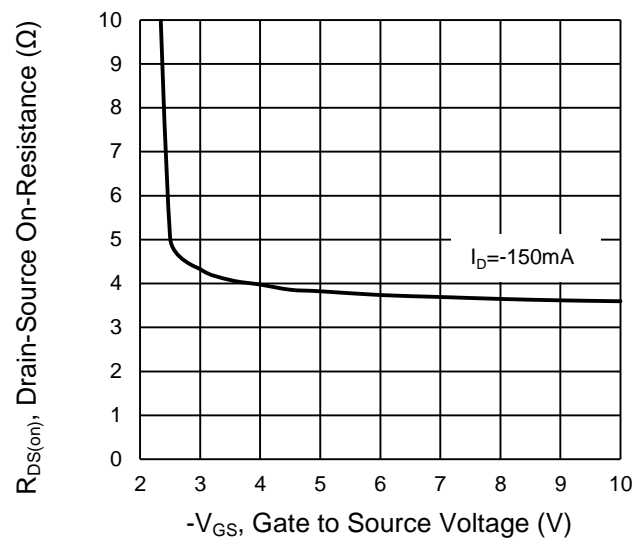
Gate-Source Voltage vs. Gate Charge



On-Resistance vs. Junction Temperature



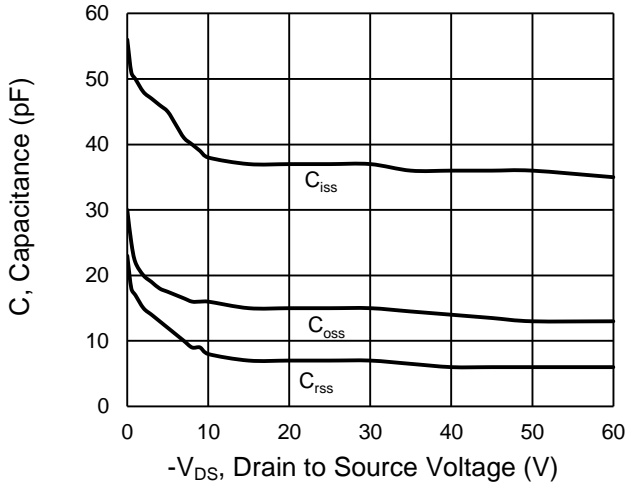
On-Resistance vs. Gate-Source Voltage



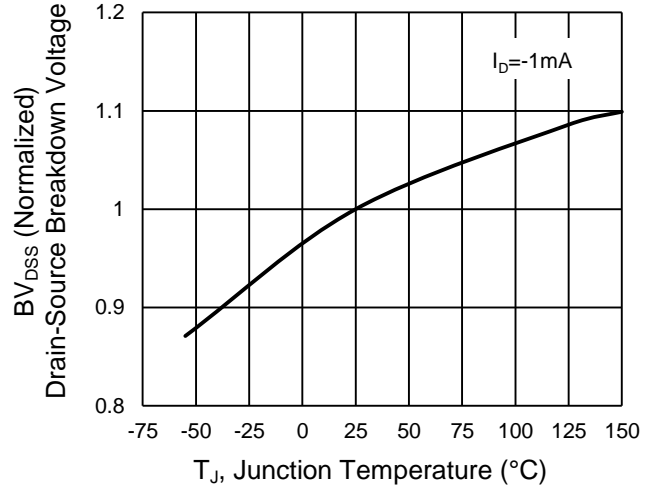
CHARACTERISTICS CURVES

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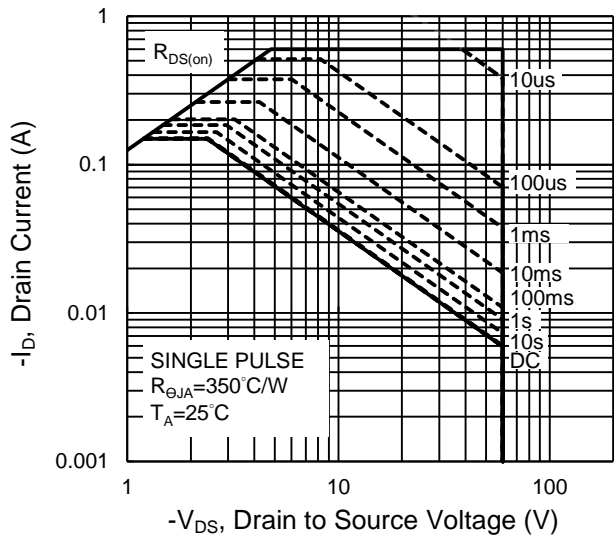
Capacitance vs. Drain-Source Voltage



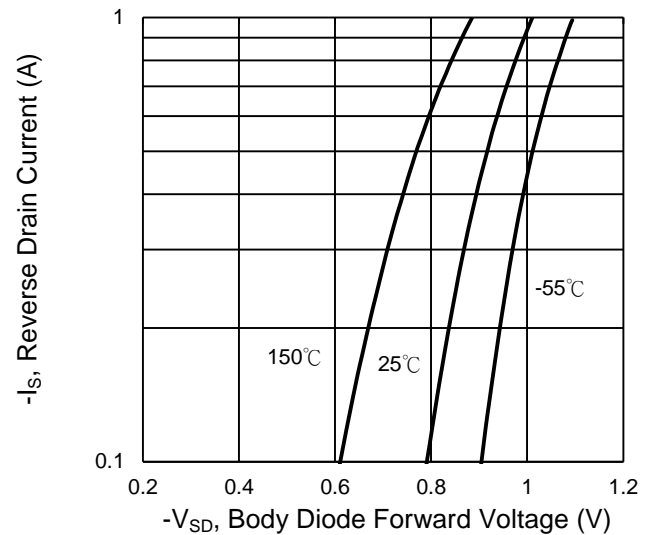
BV_{DSS} vs. Junction Temperature



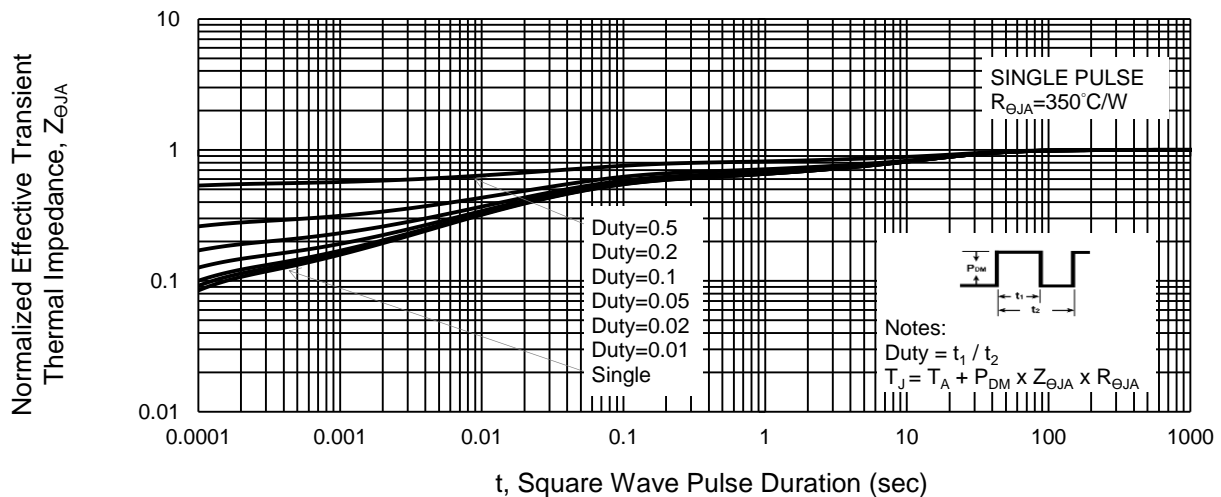
Maximum Safe Operating Area, Junction-to-Ambient



Source-Drain Diode Forward Current vs. Voltage

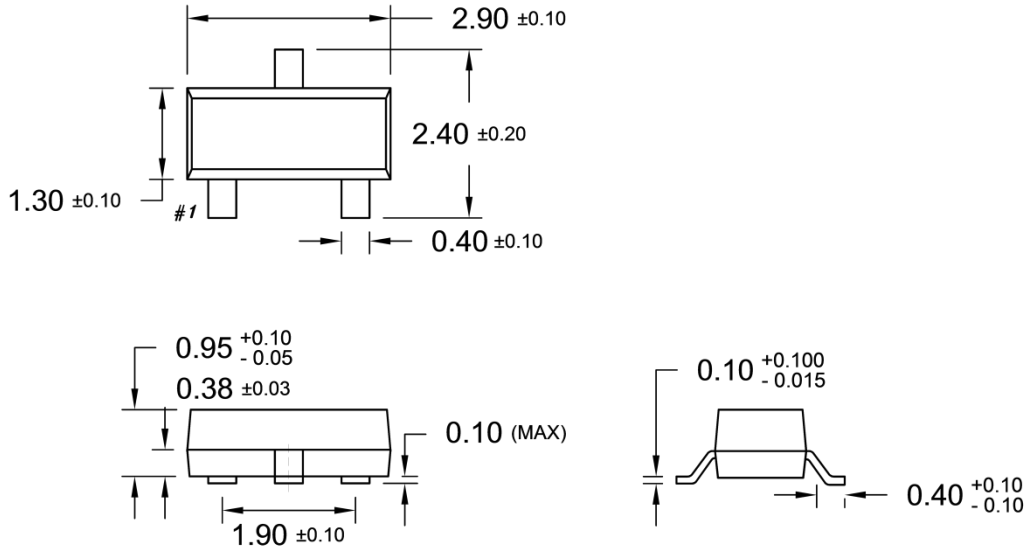


Normalized Thermal Transient Impedance, Junction-to-Ambient

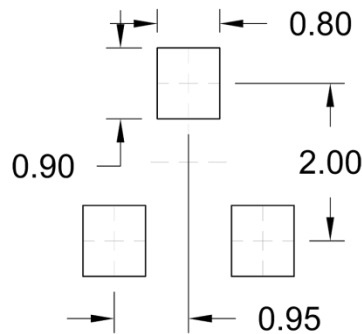


PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

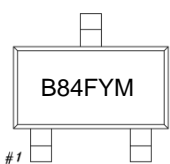
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SUGGESTED PAD LAYOUT (Unit: Millimeters)



MARKING DIAGRAM



- B84** = Device code
 - F** = Site Code
 - Y** = Year Code
 - M** = Month code
- | | | | |
|---------------|---------------|---------------|---------------|
| O =Jan | P =Feb | Q =Mar | R =Apr |
| S =May | T =Jun | U =Jul | V =Aug |
| W =Sep | X =Oct | Y =Nov | Z =Dec |

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